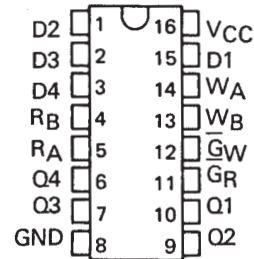


SN54LS670, SN74LS670 4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

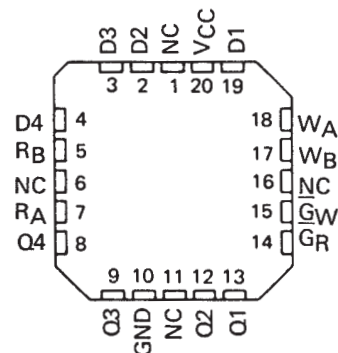
SDLS193 – MARCH 1974 – REVISED MARCH 1988

- Separate Read/Write Addressing Permits Simultaneous Reading and Writing
- Fast Access Times . . . Typically 20 ns
- Organized as 4 Words of 4 Bits
- Expandable to 512 Words of n-Bits
- For Use as:
 - Scratch-Pad Memory
 - Buffer Storage between Processors
 - Bit Storage in Fast Multiplication Designs
- 3-State Outputs
- SN54LS170 and SN74LS170 Are Similar But Have Open-Collector Outputs

SN54LS670 . . . J OR W PACKAGE
SN74LS670 . . . D OR N PACKAGE
(TOP VIEW)



SN54LS670 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection.

description

The SN54LS670 and SN74LS670 MSI 16-bit TTL register files incorporate the equivalent of 98 gates. The register file is organized as 4 words of 4 bits each and separate on-chip decoding is provided for addressing the four word locations to either write-in or retrieve data. This permits simultaneous writing into one location and reading from another word location.

Four data inputs are available which are used to supply the 4-bit word to be stored. Location of the word is determined by the write-address inputs A and B in conjunction with a write-enable signal. Data applied at the inputs should be in its true form. That is, if a high-level signal is desired from the output, a high-level is applied at the data input for that particular bit location. The latch inputs are arranged so that new data will be accepted only if both internal address gate inputs are high. When this condition exists, data at the D input is transferred to the latch output. When the write-enable input, \overline{G}_W , is high, the data inputs are inhibited and their levels can cause no change in the information stored in the internal latches. When the read-enable input, \overline{G}_R , is high, the data outputs are inhibited and go into the high-impedance state.

The individual address lines permit direct acquisition of data stored in any four of the latches. Four individual decoding gates are used to complete the address for reading a word. When the read address is made in conjunction with the read-enable signal, the word appears at the four outputs.

This arrangement—data-entry addressing separate from data-read addressing and individual sense line—eliminates recovery times, permits simultaneous reading and writing, and is limited in speed only by the write time (27 nanoseconds typical) and the read time (24 nanoseconds typical). The register file has a nondestructive readout in that data is not lost when addressed.

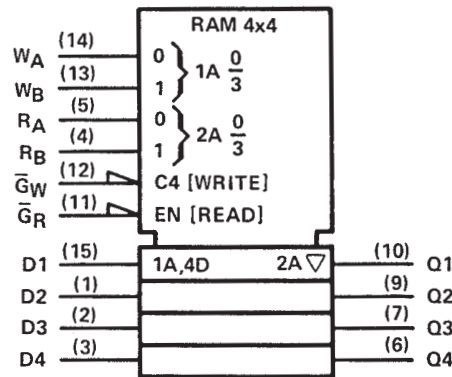
All inputs except read enable and write enable are buffered to lower the drive requirements to one Series 54LS/74LS standard load, and input-clamping diodes minimize switching transients to simplify system design. High-speed, double-ended AND-OR-INVERT gates are employed for the read-address function and have high-sink-current, three-state outputs. Up to 128 of these outputs may be bus connected for increasing the capacity up to 512 words. Any number of these registers may be paralleled to provide n-bit word length.

The SN54LS670 is characterized for operation over the full military temperature range of -55°C to 125°C ; the SN74LS670 is characterized for operation from 0°C to 70°C .

SN54LS670, SN74LS670 4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

SDLS193 – MARCH 1974 – REVISED MARCH 1988

logic symbol†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

WRITE FUNCTION TABLE (SEE NOTES A, B, AND C)

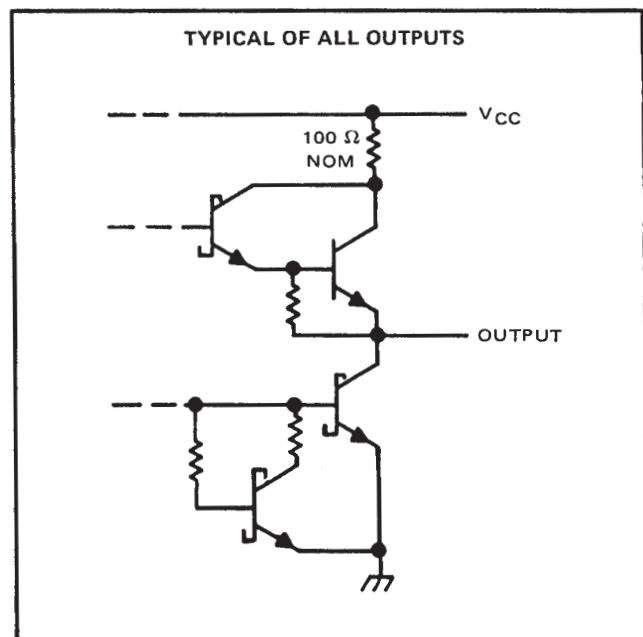
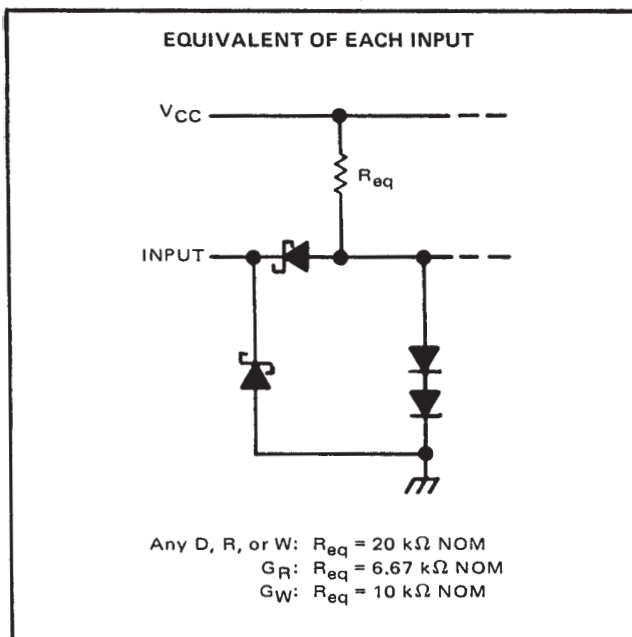
WRITE INPUTS			WORD			
W _B	W _A	G _W	0	1	2	3
L	L	L	Q = D	Q ₀	Q ₀	Q ₀
L	H	L	Q ₀	Q = D	Q ₀	Q ₀
H	L	L	Q ₀	Q ₀	Q = D	Q ₀
H	H	L	Q ₀	Q ₀	Q ₀	Q = D
X	X	H	Q ₀	Q ₀	Q ₀	Q ₀

READ FUNCTION TABLE (SEE NOTES A AND D)

READ INPUTS			OUTPUTS			
R _B	R _A	G _R	Q1	Q2	Q3	Q4
L	L	L	W0B1	W0B2	W0B3	W0B4
L	H	L	W1B1	W1B2	W1B3	W1B4
H	L	L	W2B1	W2B2	W2B3	W2B4
H	H	L	W3B1	W3B2	W3B3	W3B4
X	X	H	Z	Z	Z	Z

- NOTES: A. H = high level, L = low level, X = irrelevant, Z = high impedance (off)
 B. (Q = D) = The four selected internal flip-flop outputs will assume the states applied to the four external data inputs.
 C. Q₀ = the level of Q before the indicated input conditions were established.
 D. W0B1 = The first bit of word 0, etc.

schematics of inputs and outputs

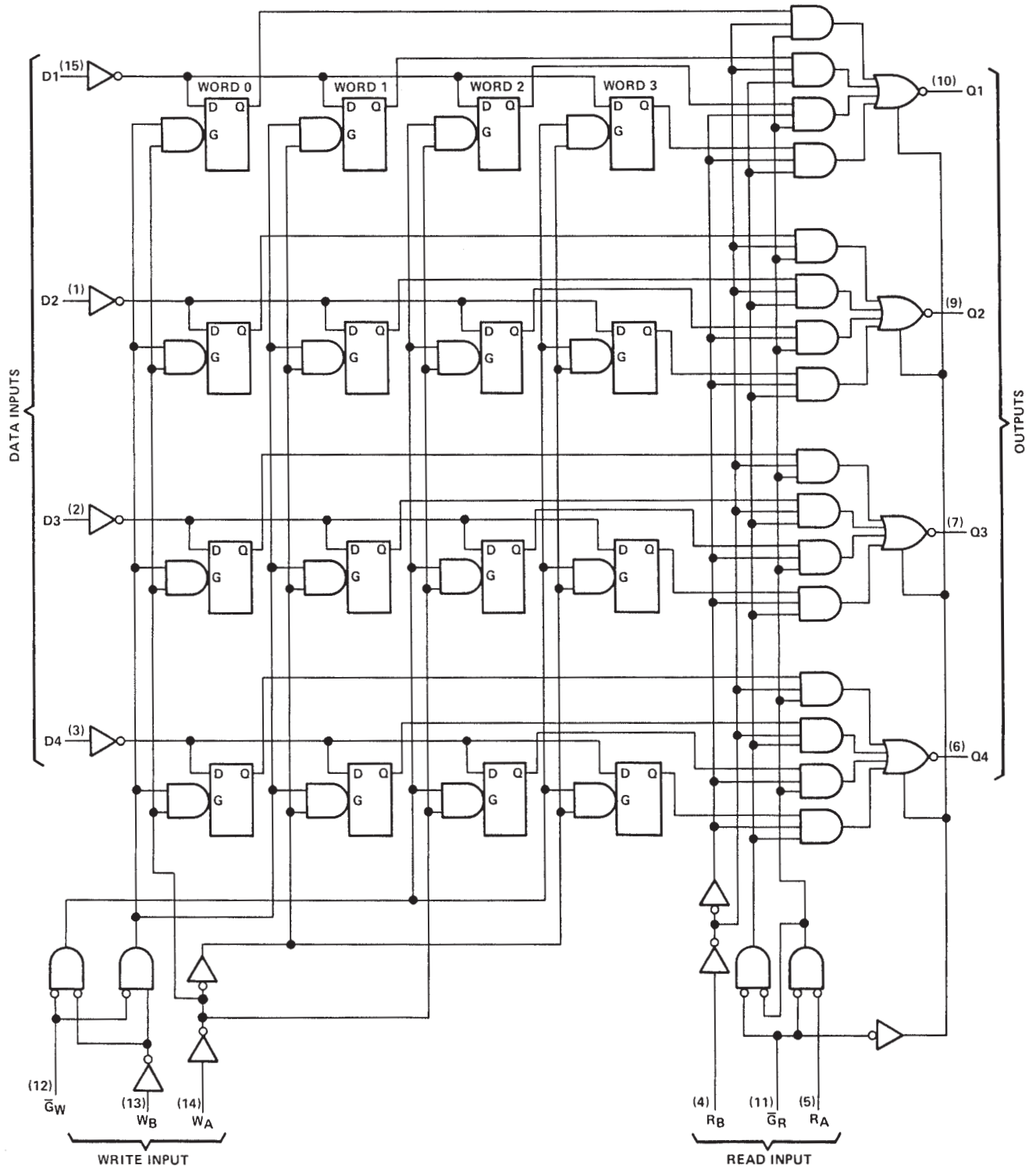


SN54LS670, SN74LS670

4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

SDLS193 – MARCH 1974 – REVISED MARCH 1988

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.



SN54LS670, SN74LS670

4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

SDLS193 – MARCH 1974 – REVISED MARCH 1988

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	7 V
Off-state output voltage	5.5 V
Operating free-air temperature range: SN54LS670	-55°C to 125°C
SN74LS670	0°C to 70°C
Storage temperature range	-65°C to 150°C

recommended operating conditions

	SN54LS670			SN74LS670			UNIT		
	MIN	NOM	MAX	MIN	NOM	MAX			
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V		
High-level output current, I_{OH}			-1			-2.6	mA		
Low-level output current, I_{OL}			4			8	mA		
Width of write-enable or read-enable pulse, t_W	25			25			ns		
Setup times, high- or low-level data (see Figure 2)	Data input with respect to write enable, $t_{SU}(D)$		10	10			ns		
	Write select with respect to write enable, $t_{SU}(W)$		15	15			ns		
Hold times, high- or low-level data (see Note 2 and Figure 2)	Data input with respect to write enable, $t_H(D)$		15	15			ns		
	Write select with respect to write enable, $t_H(W)$		5	5			ns		
Latch time for new data, t_{latch} (see Note 3)	25			25			ns		
Operating free-air temperature range, T_A	-55			125			0	70	°C

- NOTES:
1. Voltage values are with respect to network ground terminal.
 2. Write-select setup time will protect the data written into the previous address. If protection of data in the previous address is not required, $t_{SU}(W)$ can be ignored as any address selection sustained for the final 30 ns of the write-enable pulse and during $t_H(W)$ will result in data being written into that location. Depending on the duration of the input conditions, one or a number of previous addresses may have been written into.
 3. Latch time is the time allowed for the internal output of the latch to assume the state of new data. See Figure 2. This is important only when attempting to read from a location immediately after that location has received new data.



SN54LS670, SN74LS670

4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

SDLS193 – MARCH 1974 – REVISED MARCH 1988

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS670			SN74LS670			UNIT	
		MIN	TYP‡	MAX	MIN	TYP‡	MAX		
V _{IH} High-level input voltage		2			2			V	
V _{IL} Low-level input voltage				0.7			0.8	V	
V _{IK} Input clamp voltage	V _{CC} = MIN, I _I = -18 mA			-1.5			-1.5	V	
V _{OH} High-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = V _{IL max}	I _{OH} = -1 mA			2.4	3.4		V	
		I _{OH} = -2.6 mA					2.4 3.1		
V _{OL} Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = V _{IL max}	I _{OL} = 4 mA			0.25	0.4	0.25 0.4	V	
		I _{OL} = 8 mA					0.35 0.5		
I _{OZH} Off-state output current, high-level voltage applied	V _{CC} = MAX, V _{IH} = 2 V, V _O = 2.7 V			20			20	μA	
I _{OZL} Off-state output current, low-level voltage applied	V _{CC} = MAX, V _{IH} = 2 V, V _O = 0.4 V			-20			-20	μA	
I _I Input current at maximum input voltage	V _{CC} = MAX, V _I = 7 V	Any D, R, or W					0.1	0.1	mA
		\bar{G}_W					0.2	0.2	
		\bar{G}_R					0.3	0.3	
I _{IH} High-level input current	V _{CC} = MAX, V _I = 2.7 V	Any D, R, or W					20	20	μA
		\bar{G}_W					40	40	
		\bar{G}_R					60	60	
I _{IL} Low-level input current	V _{CC} = MAX, V _I = 0.4 V	Any D, R, or W					-0.4	-0.4	mA
		\bar{G}_W					-0.8	-0.8	
		\bar{G}_R					-1.2	-1.2	
I _{OS} Short-circuit output current§	V _{CC} = MAX			-30	-130	-30	-130	mA	
I _{CC} Supply current	V _{CC} = MAX, See Note 4			30	50	30	50	mA	

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at V_{CC} = 5 V, T_A = 25°C.

§Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 4: Maximum I_{CC} is guaranteed for the following worst-case conditions: 4.5 V is applied to all data inputs and both enable inputs, all address inputs are grounded and all outputs are open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

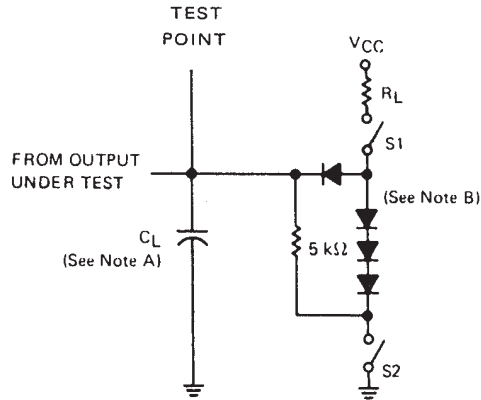
PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	Read select	Any Q	C _L = 15 pF, R _L = 2 kΩ, See Figures 1 and 2		23	40	ns
t _{PHL}					25	45	
t _{PLH}	Write enable	Any Q	C _L = 15 pF, R _L = 2 kΩ, See Figures 1 and 3		26	45	ns
t _{PHL}					28	50	
t _{PLH}	Data	Any Q	See Figures 1 and 3		25	45	ns
t _{PHL}					23	40	
t _{PZH}	Read enable	Any Q	C _L = 15 pF, R _L = 2 kΩ, See Figures 1 and 4		15	35	ns
t _{PZL}					22	40	
t _{PHZ}			See Figures 1 and 4		30	50	ns
t _{PLZ}					16	35	



SN54LS670, SN74LS670 4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

SDLS193 – MARCH 1974 – REVISED MARCH 1988

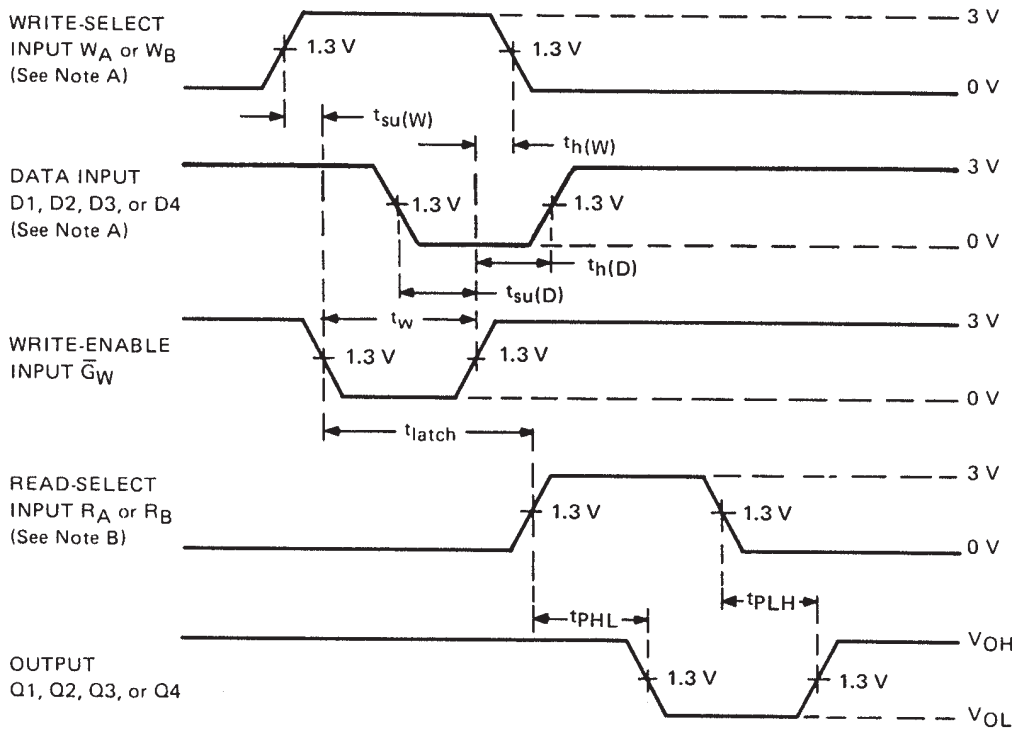
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. All diodes are 1N3064 or equivalent.

LOAD CIRCUIT

FIGURE 1



VOLTAGE WAVEFORMS (S1 AND S2 ARE CLOSED)

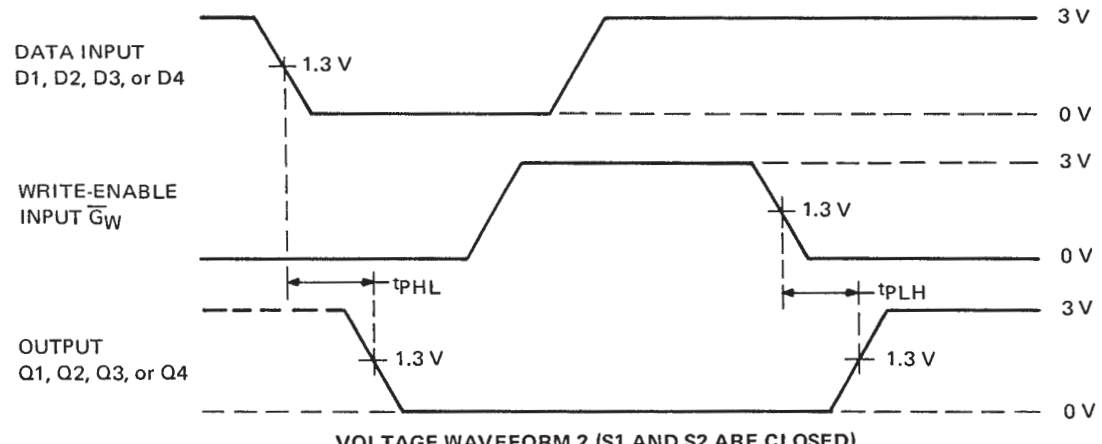
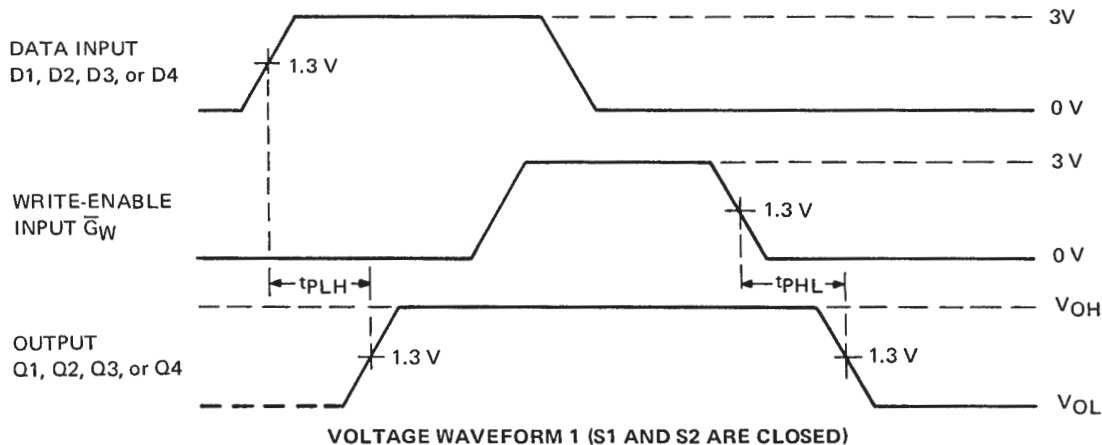
NOTES: A. High-level input pulses at the select and data inputs are illustrated; however, times associated with low-level pulses are measured from the same reference points.
B. When measuring delay times from a read-select input, the read-enable input is low.
C. Input waveforms are supplied by generators having the following characteristics: $PRR \leq 2 \text{ MHz}$, $Z_{out} \approx 50 \Omega$, duty cycle $\leq 50\%$, $t_r \leq 15 \text{ ns}$, $t_f \leq 6 \text{ ns}$.

FIGURE 2



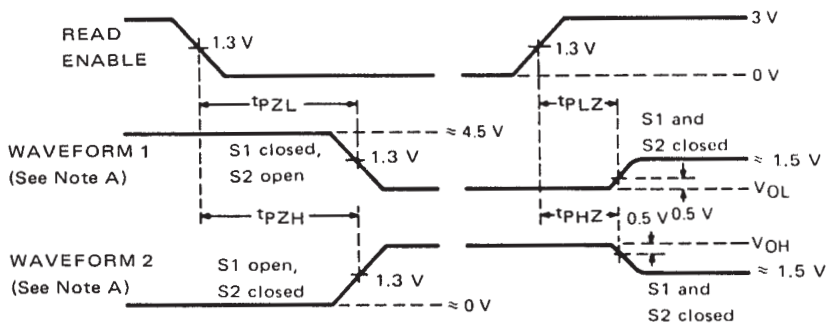
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Each select address is tested. Prior to the start of each of the above tests both write and read address inputs are stabilized with $W_A = R_A$ and $W_B = R_B$. During the test G_R is low.
B. Input waveforms are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_{out} \approx 50 \Omega$, duty cycle $\leq 50\%$, $t_r \leq 15$ ns, $t_f \leq 6$ ns.

FIGURE 3



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, THREE-STATE OUTPUTS

- NOTES: A. Waveforms 1 is for an output with internal conditions such that the output is low except when disabled by the read-enable input. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the read-enable input.
B. When measuring delay times from the read-enable input, both read-select inputs have been established at steady states.
C. Input waveforms are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_{out} \approx 50 \Omega$, duty cycle $\leq 50\%$, $t_r \leq 15$ ns, $t_f \leq 6$ ns.

FIGURE 4

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-7704201VEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	5962-7704201VE A SNV54LS670J	Samples
5962-7704201VFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	5962-7704201VF A SNV54LS670W	Samples
5962-7704201VFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	5962-7704201VF A SNV54LS670W	Samples
7704201EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704201EA SNJ54LS670J	Samples
7704201EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704201EA SNJ54LS670J	Samples
7704201FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704201FA SNJ54LS670W	Samples
7704201FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704201FA SNJ54LS670W	Samples
SN54LS670J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS670J	Samples
SN54LS670J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS670J	Samples
SN74LS670D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS670	Samples
SN74LS670D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS670	Samples
SN74LS670DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS670	Samples
SN74LS670DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS670	Samples
SN74LS670DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS670	Samples
SN74LS670DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS670	Samples
SN74LS670N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS670N	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS670N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS670N	Samples
SN74LS670N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS670N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS670NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS670N	Samples
SN74LS670NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS670N	Samples
SN74LS670NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS670	Samples
SN74LS670NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS670	Samples
SN74LS670NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS670	Samples
SN74LS670NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS670	Samples
SN74LS670NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS670	Samples
SN74LS670NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS670	Samples
SNJ54LS670FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS670FK	Samples
SNJ54LS670FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS670FK	Samples
SNJ54LS670J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704201EA SNJ54LS670J	Samples
SNJ54LS670J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704201EA SNJ54LS670J	Samples
SNJ54LS670W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704201FA SNJ54LS670W	Samples
SNJ54LS670W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704201FA SNJ54LS670W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LS670, SN54LS670-SP, SN74LS670 :

● Catalog: [SN74LS670](#), [SN54LS670](#)

● Military: [SN54LS670](#)

● Space: [SN54LS670-SP](#)

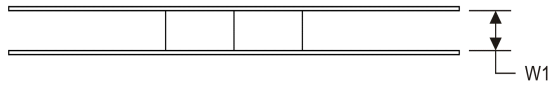
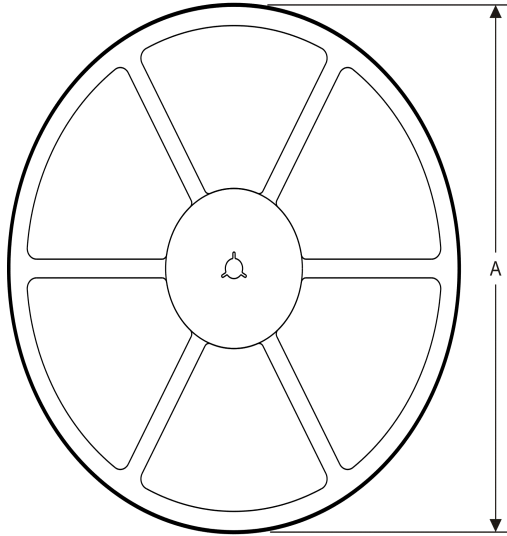
NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS670NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS670NSR	SO	NS	16	2000	367.0	367.0	38.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

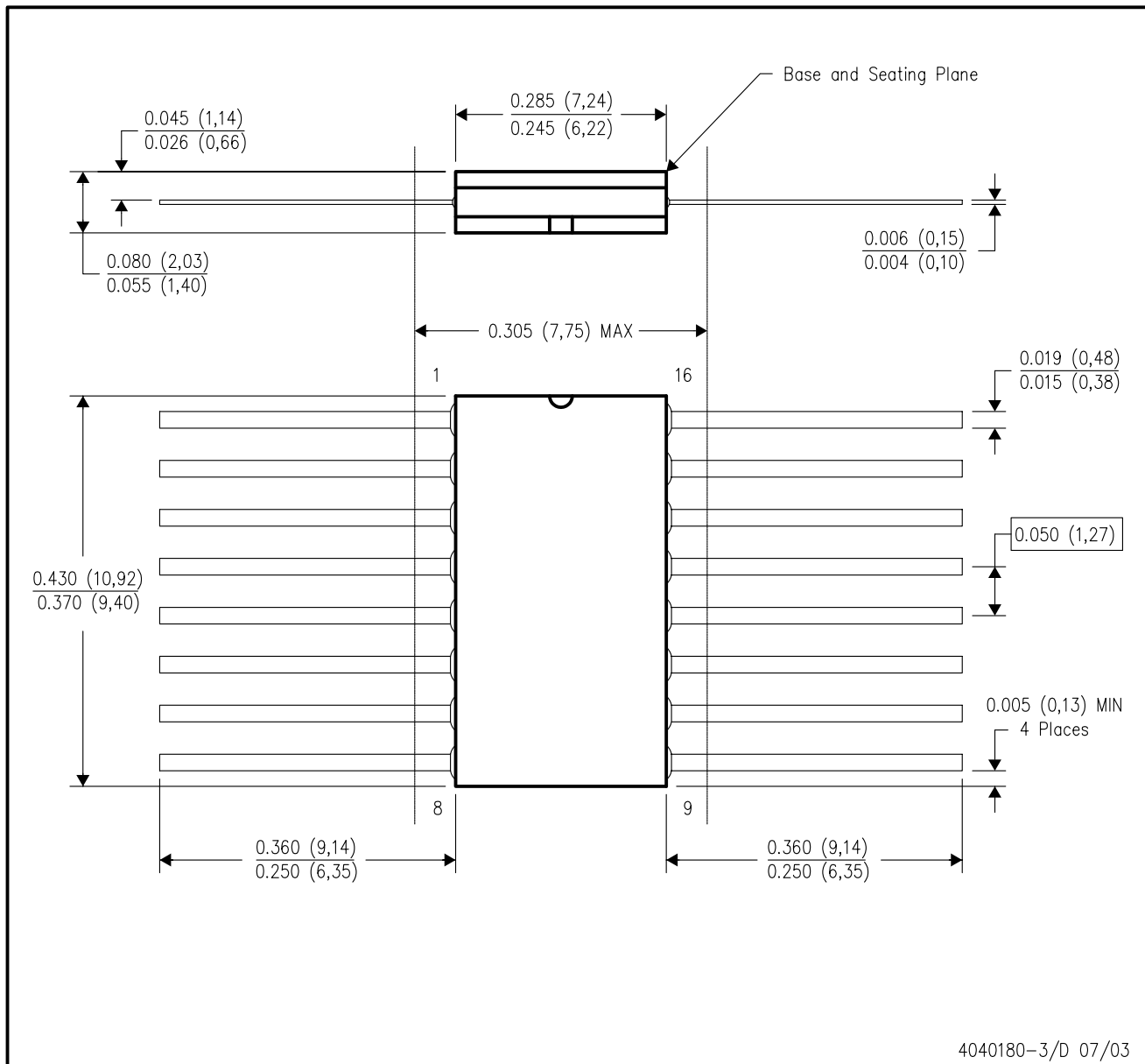


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com